

INTERCONNECTS

SERIES 850, 851, 852, 853 • 1,27 GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

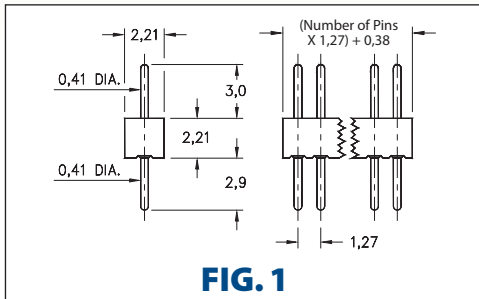


FIG. 1

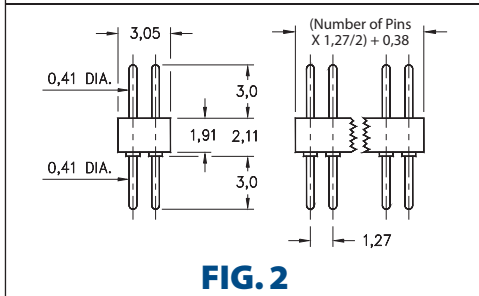


FIG. 2

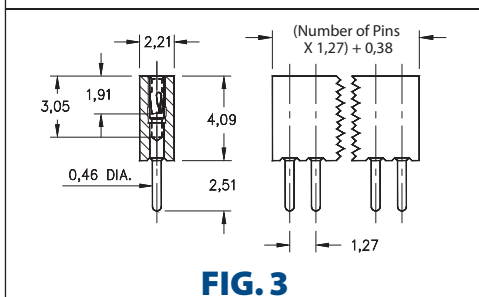


FIG. 3

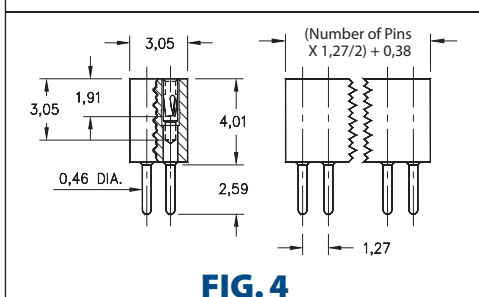


FIG. 4

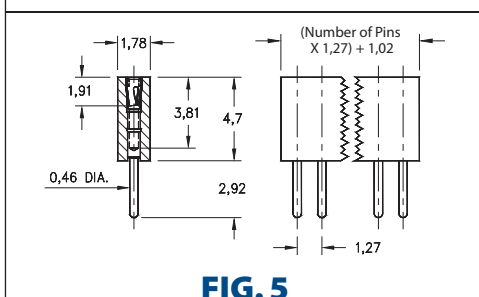
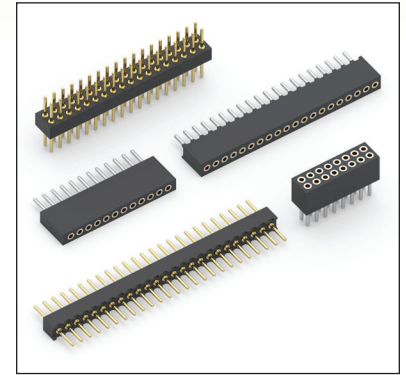


FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have 1,27 pin spacing and permit board stacking as low as 6,3
- Pin headers have 0,41 dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001 Single Row 2,21 Profile Pin Header				
	850-XX-0-10-001000 Specify number of pins 01-50				
FIG. 2	Series 852...001 Double Row 2,11 Profile Pin Header				
	852-XX-10-001000 Specify number of pins 004-100				
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264					
SPECIFY PLATING CODE XX=		10	90	40	
Pin Plating		0,25µm Au	5,08µm Sn/Pb	5,08µm Sn	

FIG. 3	Series 851...001 Single Row 4,09 Profile Socket							
	851-XX-0-10-001000 Specify number of pins 01-50							
FIG. 4	Series 853...001 Double Row 4,09 Profile Socket							
	853-XX-10-001000 Specify number of pins 004-100							
FIG. 5	Series 851...002 Single Row 4,7 Profile Socket							
	851-XX-0-10-002000 Specify number of pins 01-77							
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264								
SPECIFY PLATING CODE XX=			91	93	99	41	43	47
Sleeve (Pin)			5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn	5,08µm Sn	5,08µm Sn
Contact (Clip)			0,25µm Au	0,76µm Au	2,54µm Sn/Pb	0,25µm Au	0,76µm Au	Au Flash